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December 2013

IRF634B

N-Channel BFET MOSFET

250 V, 8.1 A, 450 m Ω

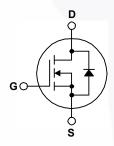
Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar, DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters and switch mode power supplies.

Features

- 8.1 A, 250 V, $R_{DS(on)}$ = 450 m Ω @ V_{GS} = 10 V
- Low Gate Charge (Typ. 29 nC)
- Low Crss (Typ. 20 pF)
- · Fast Switching
- · 100% Avalanche Tested
- · Improved dv/dt Capability





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		IRF634B_FP001	Unit	
V_{DSS}	Drain-Source Voltage		250	V	
I _D	Drain Current - Continuous (T _C = 25°C)		8.1	Α	
	- Continuous (T _C = 100°C)		5.1	Α	
I _{DM}	Drain Current - Pulsed	(Note 1)	32.4	А	
V _{GSS}	Gate-Source Voltage		± 30	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	200	mJ	
I _{AR}	Avalanche Current	(Note 1)	8.1	Α	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	7.4	mJ	
dv/dt	Peak Diode Recovery dv/dt (Note 3)		4.8	V/ns	
P_{D}	Power Dissipation (T _C = 25°C)		74	W	
	- Derate above 25°C		0.59	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	IRF634B_FP001	Unit	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	1.69	°C/W	
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink, Max.	0.5	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W	

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
IRF634B_FP001	IRF634B	TO-220	Tube	N/A	N/A	50 units

Flactrical Characteristics

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	250			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.27		V/°C
I _{DSS}	Zana Oata Vallana Busin Ourset	V _{DS} = 250 V, V _{GS} = 0 V			10	μΑ
Zero Gate Volta	Zero Gate Voltage Drain Current	Drain Current $V_{DS} = 200 \text{ V}, T_C = 125^{\circ}\text{C}$			100	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
On Cha	aracteristics					
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 4.05 A		0.345	0.45	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 4.05 A		7.6		S
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V,		780 95	1000	pF nF
C _{oss}	Output Capacitance	f = 1.0 MHz		95	125	pF
C _{rss}	Reverse Transfer Capacitance			20	25	pF
Switchi	ing Characteristics					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 125 V, I _D = 8.1 A,		15	40	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$		75	160	ns
t _{d(off)}	Turn-Off Delay Time			100	210	ns
t _f	Turn-Off Fall Time	(Note 4)	/	65	140	ns
Qg	Total Gate Charge	V _{DS} = 200 V, I _D = 8.1 A,		29	38	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V	/	4.2		nC
Q _{gd}	Gate-Drain Charge	(Note 4)		14	/	nC
Drain-S	Source Diode Characteristics a	nd Maximum Ratings				
I _S	Maximum Continuous Drain-Source Diode Forward Current				8.1	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				32.4	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 8.1 \text{ A}$			1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 8.1 A,		170		ns
Q _{rr}	Reverse Recovery Charge	dI _F / dt = 100 A/μs		0.91		μС

Notes: 1. Repetitive rating : pulse-width limited by maximum junction temperature. 2. L = 4.9 mH, I_{AS} = 8.1 A, V_{DD} = 50 V, R_G = 25 Ω , starting T_J = 25°C. 3. $I_{SD} \le$ 8.1 A, di/dt \le 300 A/ μ s, $V_{DD} \le$ BV $_{DSS}$, starting T_J = 25°C. 4. Essentially independent of operating temperature.

Typical Characteristics

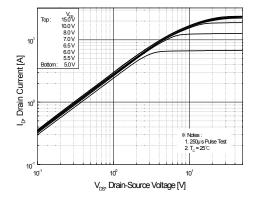


Figure 1. On-Region Characteristics

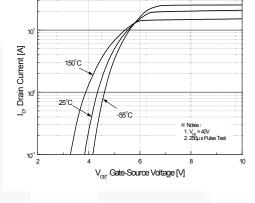


Figure 2. Transfer Characteristics

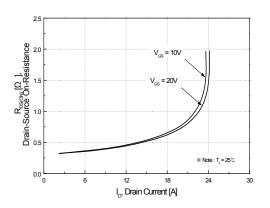


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

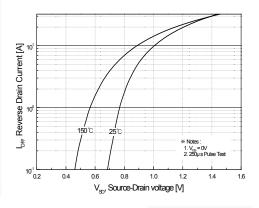


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

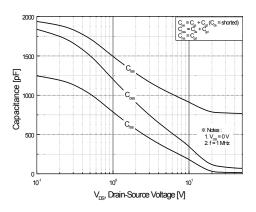


Figure 5. Capacitance Characteristics

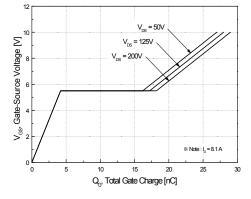
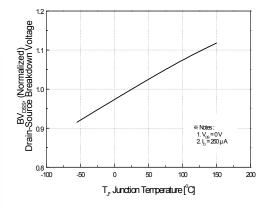


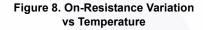
Figure 6. Gate Charge Characteristics

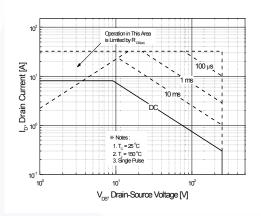
Typical Characteristics (Continued)



25 (Nomalized) 1.5 (Nomalized)

Figure 7. Breakdown Voltage Variation vs Temperature





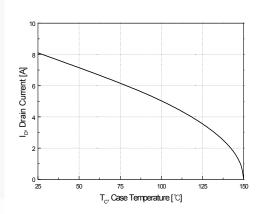


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs Case Temperature

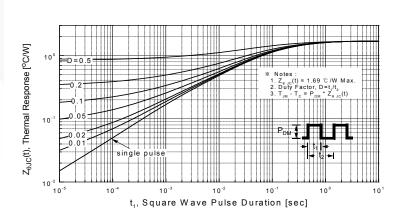


Figure 11. Transient Thermal Response Curve

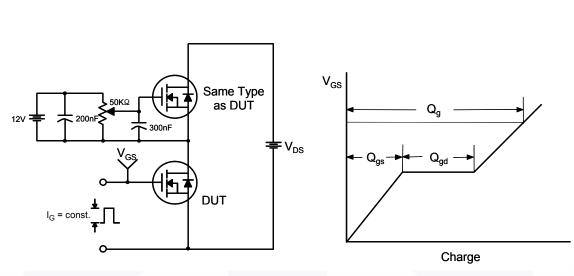


Figure 12. Gate Charge Test Circuit & Waveform

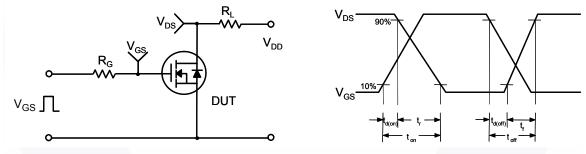


Figure 13. Resistive Switching Test Circuit & Waveforms

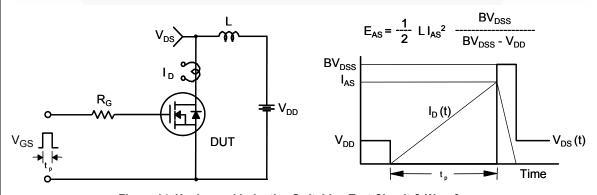
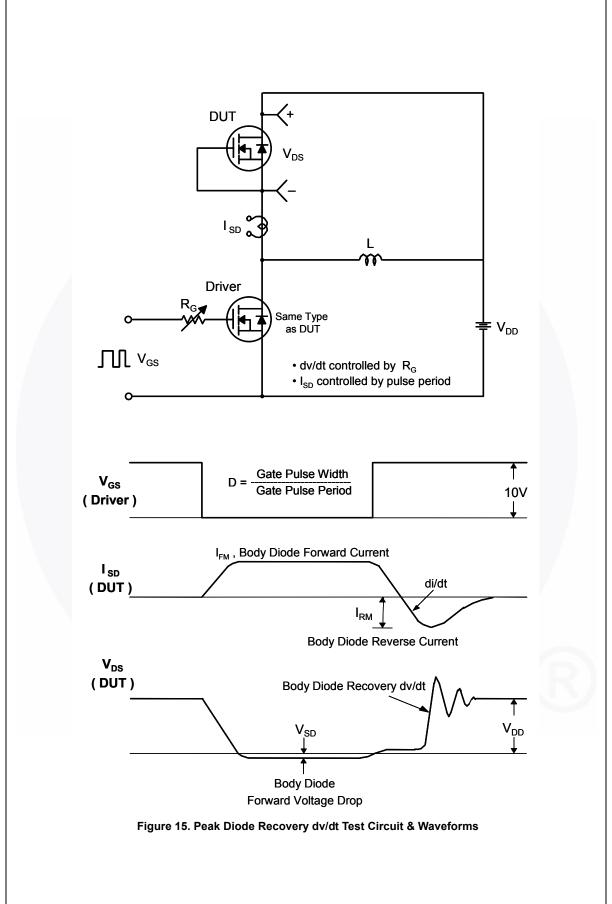


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



Mechanical Dimensions

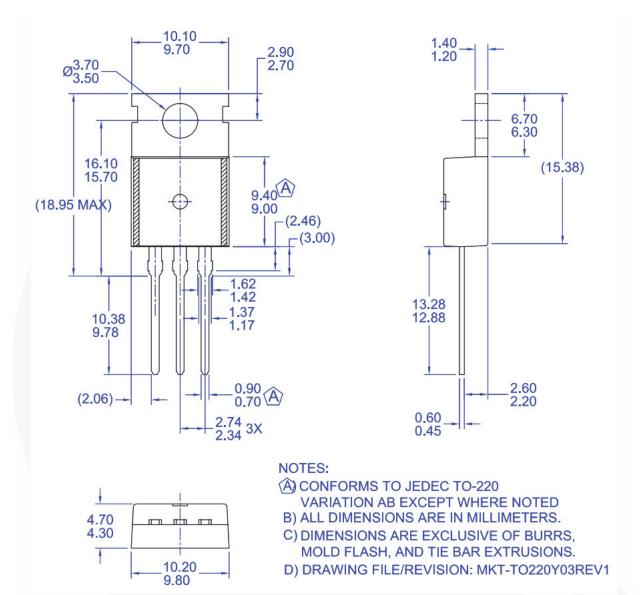


Figure 16. TO220, Molded, 3-Lead, Jedec Variation AB

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